

C1825X332MFGACTU

Aliases (C1825X332MFGAC7800)

SMD Comm COG HV Flex, Ceramic, 3,300 pF, 20%, 1,500 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1825, 2.3 mm



Click [here](#) for the 3D model.

General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	230 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1825
L	4.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	1.6mm +/-0.20mm
S	2.3mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	1500 VDC
Dielectric Withstanding Voltage	1,800 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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